



DDR x16/x8, SDRAM x32/x16 TSOP Package Internal Leadframe Design/Structure Change

PCN: 33722

Published: 2020-08-21

Type: BOM Revision

Description: Hitachi end of life'd (EOL) their Lead on Chip (LOC) tape support in August 2019. With no other LOC tape vendor to support (due to low demand), Micron and PTI have aligned to modify the TSOP package internal leadframe design/structure to eliminate LOC tape dependency and move to a Die Attach Film (DAF) solution.

Impacted Technology/Configuration: DDR1 x16/x8, SDRAM x32/x16 (TSOP Only)

Impacted Part Temperature Range: XIT, IT, CT

Any questions regarding the details in this notification should be directed to your Micron Sales or Marketing Representative.

Reason: Supply Flexibility/Security

Product Affected: Y66A Y65A Y64A T67A T66A -TSOP

Affected Micron Part Number	Recommended Replacement	Customer Part Number
<u>DRAM</u>		
MT46V16M16P-5B XIT:M		557-1917-2-ND
MT46V16M16P-5B:M		557-1915-2-ND
MT46V32M16P-5B ITJ		
MT46V32M16P-5B XITJ		
MT46V32M16P-5B:J		557-1918-2-ND
MT46V64M8P-5BJ		
MT48LC16M16A2P-6A IT:G		557-1938-2-ND, ?
MT48LC16M16A2P-6A XIT:G		557-1939-2-ND, ?
MT48LC16M16A2P-6A:G		?
MT48LC2M32B2P-6A ITJ		
MT48LC32M8A2P-6A:G		557-1943-2-ND
MT48LC4M16A2P-6A ITJ		
MT48LC4M16A2P-6A:J		MT48LC4M16A2P-6A:J-ND
MT48LC4M32B2P-6A IT:L		557-1608-2-ND, ?
MT48LC4M32B2P-6A XIT:L		557-1954-2-ND
MT48LC4M32B2P-6A:L		557-1952-2-ND, MT48LC4M32B2P-6A:L-ND
MT48LC8M16A2P-6A IT:L		557-1959-2-ND
MT48LC8M16A2P-6A XIT:L		557-1960-2-ND
MT48LC8M16A2P-6A:L		?, 557-1958-2-ND

*Materials that have been ordered are in bold.

Method of Identification: Date Code

Micron Sites Affected: Subcontractor

Sample Available: 2020-08-30

Qual Data Available: 2020-08-30

Product Ship Date: 2020-11-28

NOTE: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change.

Micron Confidential and Proprietary Information

Attachments
